



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

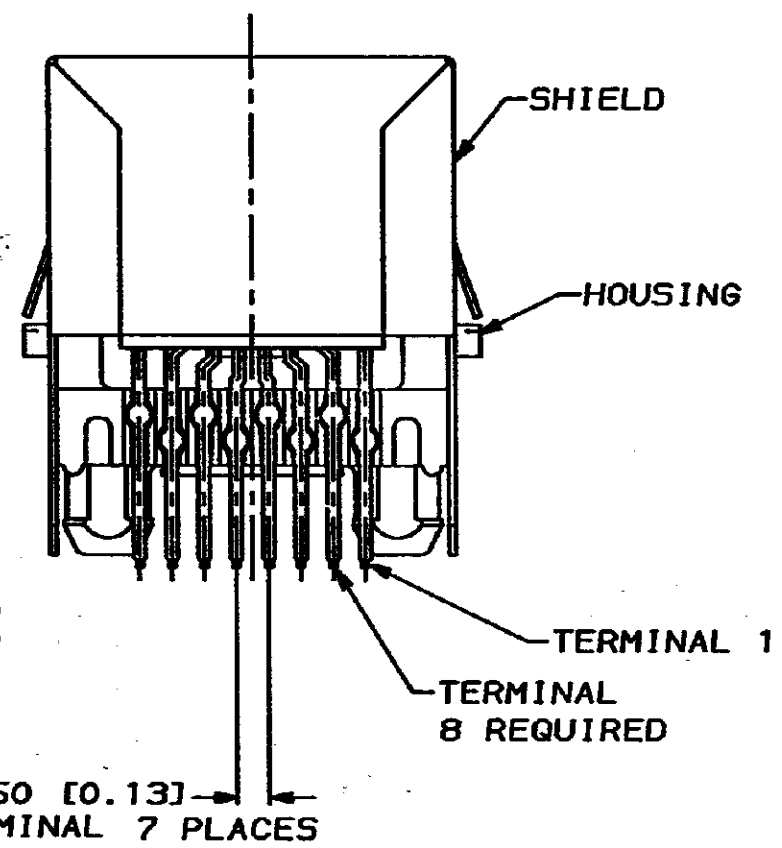
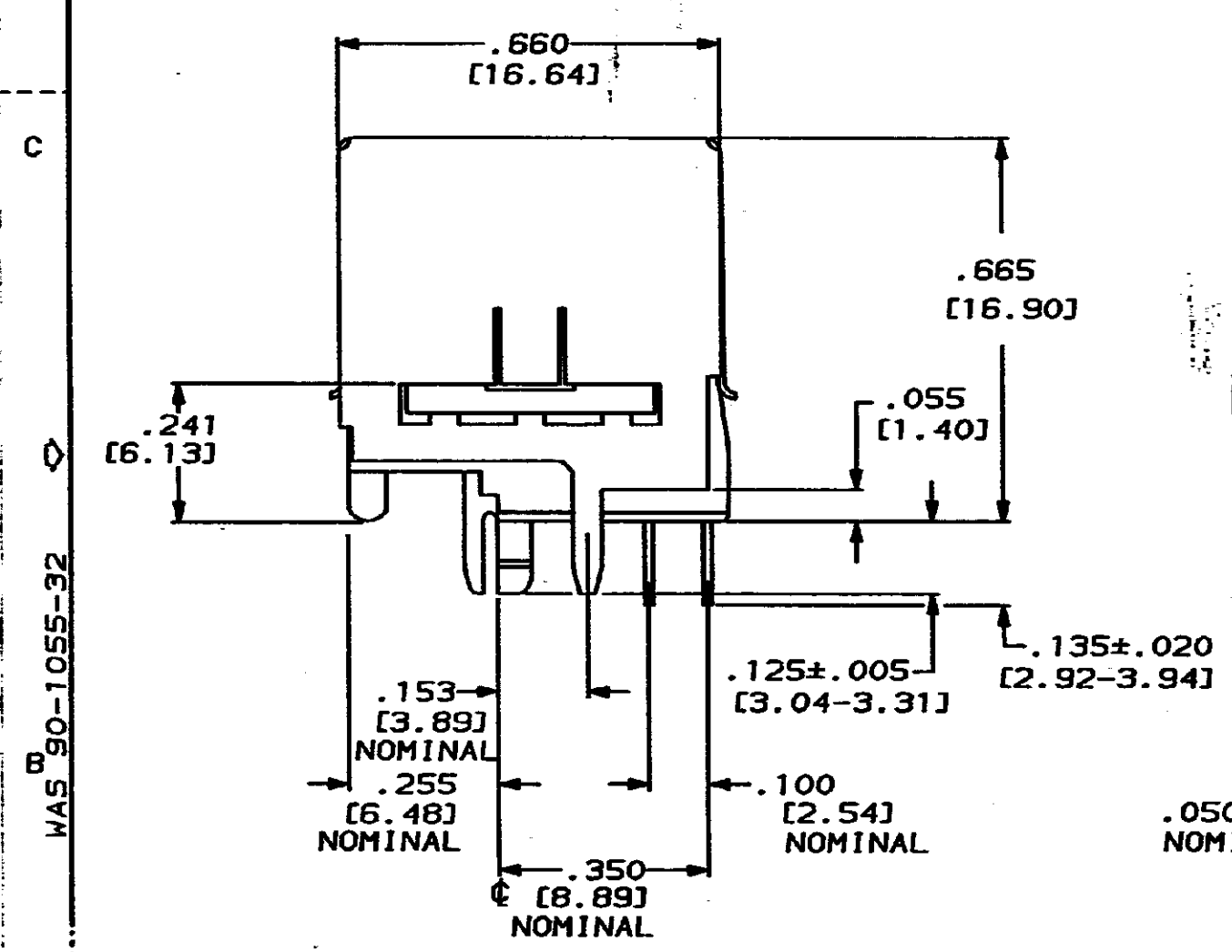
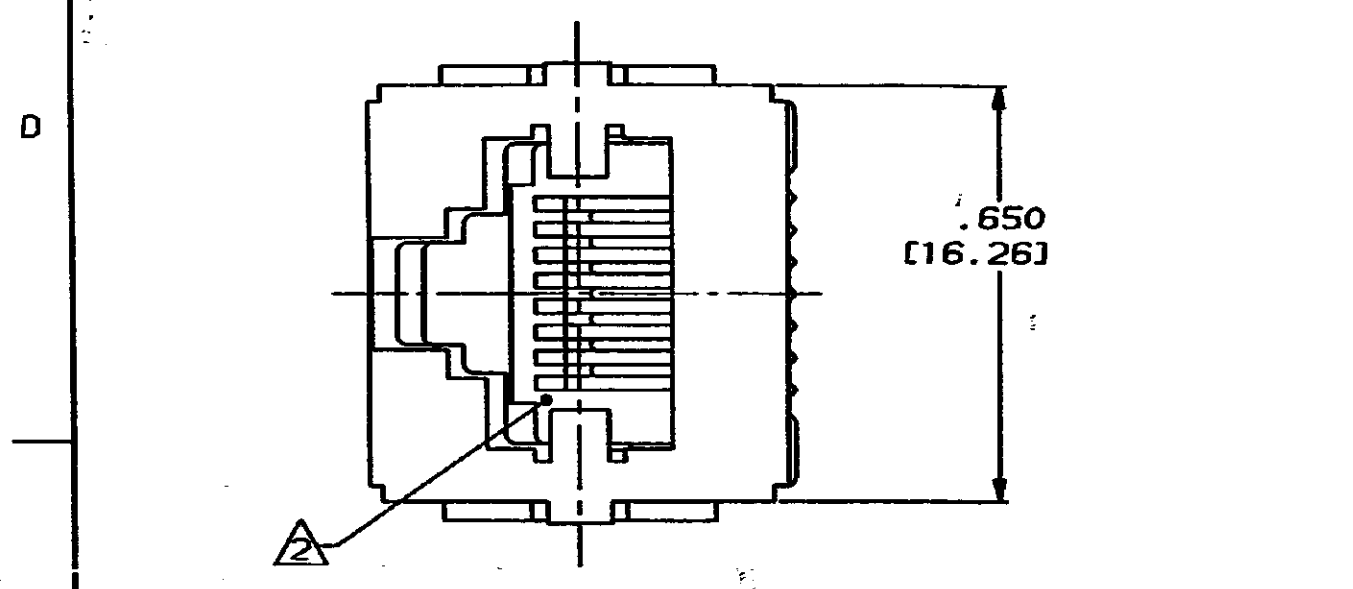
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

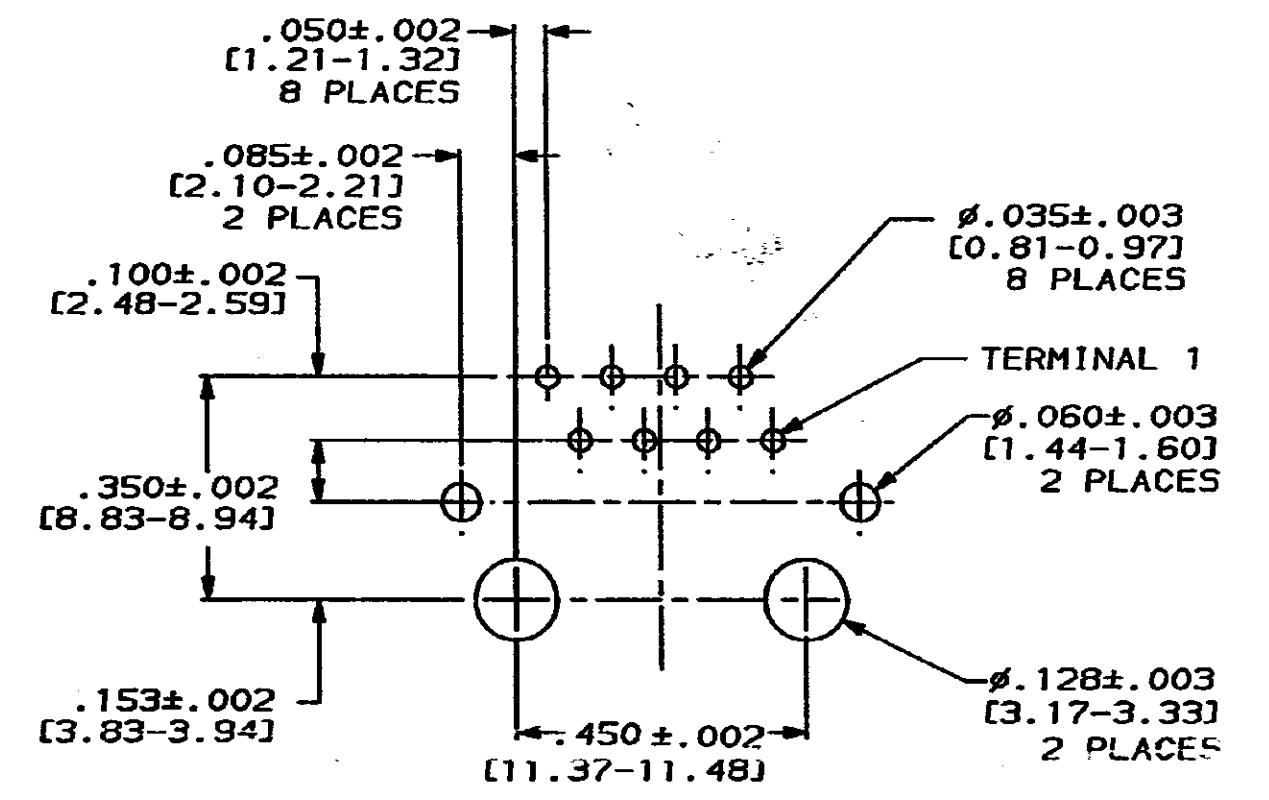


DRAWING MADE IN THIRD ANGLE PROJECTION
 THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION
 © COPYRIGHT 19 BY AMP INCORPORATED. ALL INTERNATIONAL RIGHTS RESERVED.

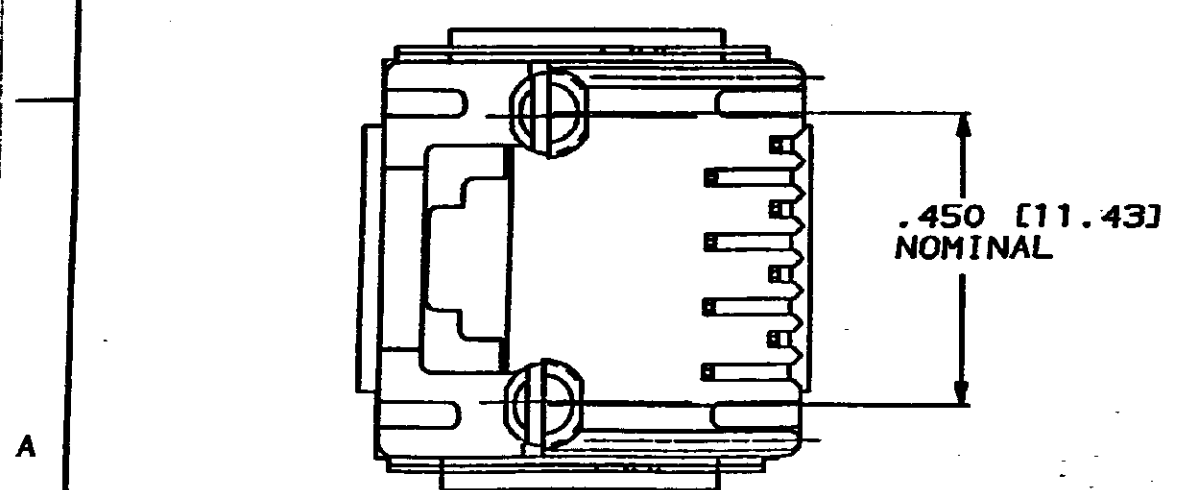
LOG	DIST	P	F	ZONE	LTR	REVISIONS	DATE	APPD
AA	22				A	REV, ECN AA-8462	5-5-92	RS



- △ MATERIAL: HOUSING- POLYESTER MOLDING COMPOUND, BLACK. TERMINALS- .0138 [0.350] THICK PHOS BRONZE PLATED WITH .000050 [1.27um] MINIMUM THICK GOLD IN LOCALIZED AREA AND .000150 [3.81um] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER .000050 [1.27um] MINIMUM THICK NICKLE UNDERPLATE. SHIELD- COPPER ZINC ALLOY PLATED WITH .000080 [2.03um] MINIMUM THICK TIN-LEAD OVER .000100 [2.54um] MINIMUM THICK COPPER UNDERPLATE.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3. FOR APPLICATION INFORMATION SEE AMP SPECIFICATION 114-2048.
- 4. FOR PERFORMANCE REQUIREMENTS SEE AMP SPECIFICATION 108-1163.
- △ DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 6. BULK PACKAGED IN A TRAY.
- 7. DIMENSIONS IN BRACKETS [] ARE IN MILLIMETERS.



VIEW SHOWN IS CIRCUIT (NONCOMPONENT)
 SIDE OF PC BOARD HOLE LAYOUT



CAD DRAWINGS
 THIS DRAWING WAS CREATED ON A COMPUTER AIDED DESIGN (CAD) SYSTEM TO INSURE THE INTEGRITY OF THE DATA BASE. ALL CHANGES/REVISIONS MUST BE MADE ON THE CAD SYSTEM.

		557484-1	
		PART NO	
DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN INCHES [mm]	DR RB. INZERILLO 12-03-91	AMP AMP Incorporated Harrisburg, PA 17105-3608	
TOLERANCES ON:	CHK D. HUSSEY 3-24-92		
2 PLC DEC ±	APPD J. TONEY 4-2-92	NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL STOPS, PANEL & PCB GROUNDS	
3 PLC DEC ±	APPD J. TONEY 4-2-92		
ANGLES ±	PRODUCT SPEC	SIZE CAGE CODE DRAWING NO C 00779 557484	
MATERIAL	FINISH		
	APPLICATION SPEC	SCALE 4:1 SHEET 1 OF 1	
	WEIGHT		

CAD CUSTOMER DRAWING